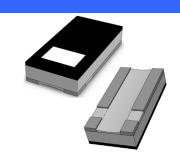
RL0816T4F-7 Series Current Sensor Resistor (Lead / Halogen Free)

Features / Applications:

- High power rating is up to 1/6W
- Low TCR current sensor
- Resistors are ideal for all types of current sensing
- Metal film construction; Excellent long-term stability
- Moisture sensitivity level: MSL 1
- RoHS compliant



Electrical Specifications:

| Characteristics ¹ | Feature |
|---|-----------------------|
| Power Rating ² | 1/6 W |
| Resistance Value(mΩ) | 5 to 100 |
| Temperature Coefficient of Resistance(ppm/°C) | ± 150 |
| Operation Temperature Range | 55°C to +125°C |
| Maximum Working Voltage (V) | (P*R) ^{1/2} |

Note:

- 1. For detailed information see table on page 3
- 2. For sensors operated at ambient temperature in excess of 70°C, the maximum load shall be derated in accordance with the following curve.

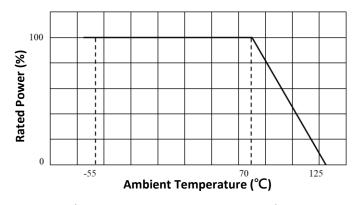
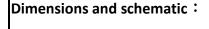


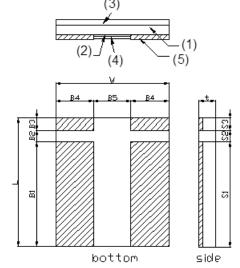
Figure 1. : Power Temperature Derating Curve

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Outline Drawing:





- (1) Substrate
- (2) Resistor : Cu alloy
- (3) Protection coat:

Heat resistive epoxy resin (Black)

(4) Protection coat:

Heat resistive epoxy resin (White)

(5) Terminals: Sn (on Cu)

| Resistance Range(mΩ) | L | W | S1 | S2 | S3 | t |
|----------------------|-----------|-----------|-----------|-----------|-----------|-----------|
| | 1.60±0.20 | 0.80±0.15 | 1.10±0.20 | 0.25±0.10 | 0.25±0.10 | 0.50±0.20 |
| 5 to 100 | B1 | B2 | В3 | В4 | В5 | |
| | 1.10±0.20 | 0.25±0.10 | 0.25±0.10 | 0.20±0.10 | 0.40±0.20 | |

(Unit:mm)

Type Designation:

RL 0816T4F - 7 - | NH

(1) (2) (3) (4) (5)

Note:

(1) Series No.

(2) Size(T4F = 4 - terminal)

(3) Power Rating :7 = 1/6W

(4) Resistance value : $0R5m = 0.5m\Omega$; $R002 = 2m\Omega$; $R010 = 10m\Omega$

(5) Tolerance: ±1%(F), ±2%(G), ±3%(H), ±5%(J)

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Available standard resistance values:

| Decistance Volume | Tolerance | | | | |
|-------------------|-----------|----------|-------|-------|--|
| Resistance Values | ±0.5% | ±1.0% | ±2.0% | ±5.0% | |
| R005 | | ✓ | ✓ | ✓ | |
| R006 | | ✓ | ✓ | ✓ | |
| R007 | | ✓ | ✓ | ✓ | |
| R008 | | ✓ | ✓ | ✓ | |
| R009 | | ✓ | ✓ | ✓ | |
| R010 | ✓ | ✓ | ✓ | ✓ | |
| R015 | | ✓ | ✓ | ✓ | |
| R020 | | ✓ | ✓ | ✓ | |
| R025 | | ✓ | ✓ | ✓ | |
| R030 | | ✓ | ✓ | ✓ | |
| R033 | | ✓ | ✓ | ✓ | |
| R035 | | ✓ | ✓ | ✓ | |
| R040 | | ✓ | ✓ | ✓ | |
| R047 | | ✓ | ✓ | ✓ | |
| R050 | | ✓ | ✓ | ✓ | |
| R075 | | ✓ | ✓ | ✓ | |
| R100 | | ✓ | ✓ | ✓ | |

√= available

Further values and tolerances on request.

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Reliability Performance:

| Test Item | Condition of Test | Requirements |
|------------------------------|--|---|
| Short Time Overload | 2.5 x Rated power for 5 seconds Refer to JIS C 5201-1 4.13 | ΔR: ±1.0% |
| Thermal Cycling | -55 to 125℃ 100 cycles, 15 min at each extreme condition Refer to JIS C 5201-1 4.19 | ΔR: ±1.0% |
| Low Temperature Storage | Kept at -55℃, 1000 hours Refer to JIS C 5201-1 4.23.4 | ΔR: ±1.0% |
| Resistance to Soldering Heat | Dipped into solder at $260 \pm 5^{\circ}$ C for 10 ± 1 seconds Refer to JIS C 5201-1 4.18 | ΔR: ±1.0% |
| Load Life | Rated voltage for 1.5hours followed by a pause 0.5hour at 70 ± 3°C Cycle repeated 1000 hours Refer to JIS C 5201-1 4.25 | ΔR: ±1.0% |
| Damp Heat with Load | 60 ± 2°C with relative humidity 90% to 95%. D.C. rated voltage for 1.5 hours ON and 30 minutes OFF. Cycle repeated 1,000 hours Refer to JIS C 5201-1 4.24 | ΔR: ±1.0% |
| High Temperature Exposure | Kept at 125℃ for 1000 hours Refer to JIS C 5201-1 4.23.2 | ΔR: ±1.0% |
| Solderability | Temperature of Solder : $245 \pm 5^{\circ}$ C Immersion Duration : 3 ± 0.5 second Refer to JIS C 5201-1 4.17 | Uniform coating of solder cover minimum of 95% surface being immersed |
| Mechanical Shock | 100 G's for 6milliseconds. 5 pulses $\Delta R : \pm 0.59$ Refer to JIS C 5201-1 4.21 | |
| Substrate Bending | Glass-Epoxy board thickness: 1.6mm Bending width: 2mm Between the fulcrums: 90mm Refer to JIS C 5201-1 4.33 | ΔR:±0.5% |

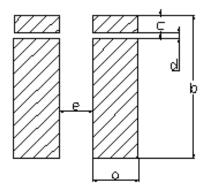
Note: Measurement at 24±4 hours after test conclusion for all reliability tests-parts.

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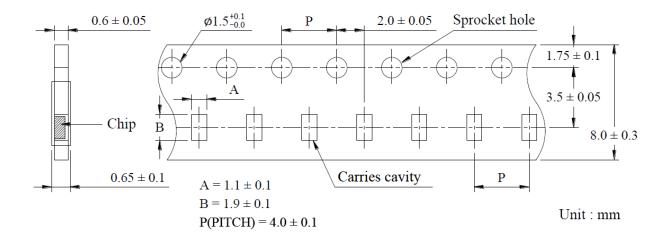
Recommend Solder Pad Dimensions:



| Dimensions (mm) | а | b | С | d | е |
|---------------------|-----|-----|-----|-----|------|
| 5 to 100 m Ω | 0.4 | 1.9 | 0.4 | 0.2 | 0.35 |

Packaging:

Tape packaging dimensions:

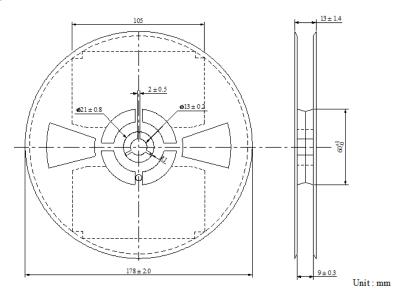


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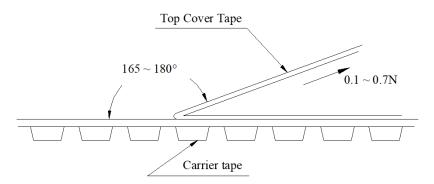
Reel dimensions:



Peel Strength of Top Cover Tape:

The peel speed shall be about 300mm/min.

The peel force of top cover tape shall between 0.1 to 0.7N



Number of Taping:

5,000 pieces / reel

Label Marking:

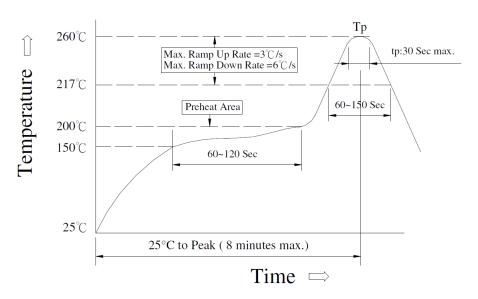
The following items shall be marked on the reel.

- (1) Type designation
- (2) Quantity
- (3) Manufacturing date code
- (4) Manufacturer's name
- (5) The country of origin

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Recommend Soldering Conditions:



Meet JEDEC-020D

(1) Reflow Soldering Method:

| Defless Calderine | Tp:255 to 260℃ Max.30 seconds (Tp) | | |
|------------------------------|--------------------------------------|--|--|
| Reflow Soldering | 217℃ 60 to 150 seconds | | |
| Pre-Heat | 150 to 200℃ 60 to 120 seconds | | |
| Time 25℃ to peak temperature | 8 minutes max | | |

(2) Soldering Iron Method: 350± 5°C max.3 seconds

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Care Note:

Care note for storage

- (1) Current sensor shall be stored in a environment where temperature and humidity must be controlled (temperature 5 to 40°C, humidity 30 to 80% RH). However, the humidity should be maintained as low as possible.
- (2) Current sensor shall not be stored under direct sunlight.
- (3) Current sensor shall be stored in condition without moisture, dust, any material defect solderability, or hazardous gas (i.e. Chlorination hydrogen, sulfurous acid gas, and sulfuration hydrogen)
- (4) The sensor can be stored for at least one year under the condition mentioned above.

Care note for operating and handling

- (1) It is necessary to protect the edge and protection coat of resistors from mechanical stress.
- (2) Handle with care when printing circuit board (PCB) is divided or fixed on support body, because bending of printing circuit board (PCB) mounting will make mechanical stress for resistors.
- (3) Resistors shall be used with in rated range shown in specification. Especially, if voltage more than specified value will be loaded to resistor, there is a case it will make damage for machine because of temperature rise depending on generating of heat, and increase resistance value or breaks.
- (4) In case that resistor is loaded a rated voltage, it is necessary to confirms temperature of a resistor and to reduce a load power according to load reduction curve, because a temperature rise of a resistor depends on influence of heat from mounting density and neighboring element.
- (5) Observe Limiting element voltage and maximum overload voltage specified in each specification
- (6) If there is possibility that a large voltage (pulse voltage, shock voltage) charge to resistor, it is necessary that operating condition shall be set up before use.

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